ABSTRACT OF THE DISCLOSURE

A semiconductor device in which inner leads among a plurality of leads are arranged on a circuit formation face of a semiconductor chip encapsulated by a resin encapsulating body and bonding pads formed on the circuit formation face of the chip and the inner leads are electrically connected. An adhesive is selectively applied only to the inner leads on the outermost sides arranged on both ends of the chip among the plurality of inner leads. The circuit formation face of the chip and the inner leads of the selected leads are joined with the adhesive. Each of the selected leads has a step on the main face of the semiconductor chip and the leads except for the selected leads have almost straight shapes without being processed to have steps.

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